# **DRC4124E**

## Silicon NPN epitaxial planar type

For digital circuits

Complementary to DRA4124E

DRC2124E in NS through hole type package

#### ■ Features

- ullet Low collector-emitter saturation voltage  $V_{\text{CE(sat)}}$
- Contributes to miniaturization of sets, mount area reduction
- Eco-friendly Halogen-free package

#### ■ Packaging

DRC4124E0A Radial type: 5000 pcs / carton

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	50	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	50	V
Collector current	$I_{C}$	100	mA
Total power dissipation	P <sub>T</sub>	300	mW
Junction temperature	$T_j$	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

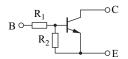
### ■ Package

• Code

NS-B2-B-B

Package dimension clicks here. $\rightarrow$ 

- Pin Name
  - 1: Emitter
  - 2: Collector
  - 3: Base
- Marking Symbol: NE
- Internal Connection



Resistance value	R <sub>1</sub>	22	kΩ
	R <sub>2</sub>	22	kΩ

### ■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = 10 \mu A, I_E = 0$	50			V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$	50			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 50 \text{ V}, I_{E} = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 50 \text{ V}, I_{B} = 0$			0.5	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 6 \text{ V}, I_{C} = 0$			0.2	mA
Forward current transfer ratio	$h_{FE}$	$V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$	60			_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$			0.25	V
Input voltage (ON)	$V_{I(on)}$	$V_{CE} = 0.2 \text{ V}, I_{C} = 5 \text{ mA}$	2.6			V
Input voltage (OFF)	$V_{I(off)}$	$V_{CE} = 5 \text{ V}, I_{C} = 100  \mu\text{A}$			0.8	V
Input resistance	R <sub>1</sub>		-30%	22	+30%	kΩ
Resistance ratio	$R_1/R_2$		0.8	1.0	1.2	_

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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